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Diodes Incorporated DMN3024SFG-7

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DMN3024SFG

30V N-CHANNEL ENHANCEMENT MODE MOSFET POWERDI[®]

Product Summary

| V _{(BR)DSS} | R _{DS(ON)} max | I _D max T _A = 25°C |
|----------------------|-----------------------------|---|
| | $23m\Omega @ V_{GS} = 10V$ | 7.5A |
| 30V | $33m\Omega @ V_{GS} = 4.5V$ | 6.3 A |

Description and Applications

This MOSFET has been designed to minimize the on-state resistance $(R_{DS(on)})$ and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

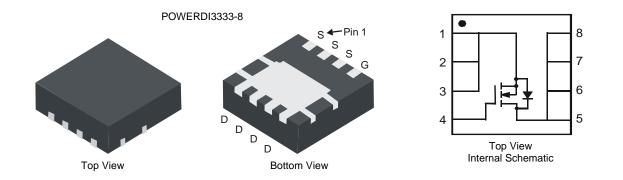
- Backlighting
- Power Management Functions
- DC-DC Converters

Features and Benefits

- 100% Unclamped Inductive Switch (UIS) test in production
- Low R_{DS(ON)} ensures on state losses are minimized
- Small form factor thermally efficient package enables higher density end products
- Occupies just 33% of the board area occupied by SO-8 enabling smaller end product
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: POWERDI3333-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See diagram
 Terminals: Finish Matte Tin annealed over Copper leadframe.
 Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.008 grams (approximate)



Ordering Information (Note 4)

| Part Number | Case | Packaging |
|---------------|---------------|------------------|
| DMN3024SFG-7 | POWERDI3333-8 | 2000/Tape & Reel |
| DMN3024SFG-13 | POWERDI3333-8 | 3000/Tape & Reel |

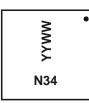
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and

<1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com.

Marking Information



N34 = Product Type Marking Code YYWW = Date Code Marking YY = Last digit of year (ex: 11 = 2011) WW = Week code (01 ~ 53)





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Maximum Ratings @T_A = 25°C unless otherwise specified

| Characteristic | Symbol | Value | Units | | |
|--|------------------|--|-------|-------------|---|
| Drain-Source Voltage | V _{DSS} | 30 | V | | |
| Gate-Source Voltage | V _{GSS} | ±25 | V | | |
| | Steady State | T _A = 25°C T _A = 70°C | ID | 7.5 6.0 | A |
| Continuous Drain Current (Note 6) $V_{GS} = 10V$ | t<10s | T _A = 25°C T _A = 70°C | ID | 10.5 8.5 | А |
| | Steady State | T _A = 25°C T _A = 70°C | ID | 6.3 5.0 | A |
| Continuous Drain Current (Note 6) $V_{GS} = 4.5V$ | t<10s | T _A = 25°C T _A = 70°C | ID | 8.5 7.6 | A |
| Pulsed Drain Current (10µs pulse, duty cycle = 1%) | I _{DM} | 60 | A | | |
| Avalanche Current (Note 7) | I _{AS} | 9 | A | | |
| Repetitive Avalanche Energy (Note 7) | E _{AS} | 12 | mJ | | |

Thermal Characteristics @T_A = 25°C unless otherwise specified

| Characteristic | Symbol | Value | Units | |
|--|-----------------------|-----------------------|-------------|------|
| Total Dower Dissinction (Note 5) | T _A = 25°C | Р | 0.9 | W |
| Total Power Dissipation (Note 5) | T _A = 70°C | PD | 0.5 | |
| Thermal Registerion Junction to Ambient (Note E) | Steady state | Р | 145 | °C/W |
| Thermal Resistance, Junction to Ambient (Note 5) | t<10s | $R_{	extsf{	heta}JA}$ | 74 | |
| Tatal Bawar Dissinction (Nata 6) | T _A = 25°C | | 2.2 | W |
| Total Power Dissipation (Note 6) | T _A = 70°C | PD | 1.4 | |
| Thermal Resistance, Junction to Ambient (Note 6) | Steady state | D | 58 | °C/W |
| mermai Resistance, Junction to Ambient (Note 6) | t<10s | $R_{	extsf{	heta}JA}$ | 31 | |
| Thermal Resistance, Junction to Case (Note 6) | $R_{\theta JC}$ | 11 | | |
| Operating and Storage Temperature Range | | TJ, TSTG | -55 to +150 | °C |

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout. 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. 7 .UIS in production with L = 0.3mH, TJ = 25° C Notes:



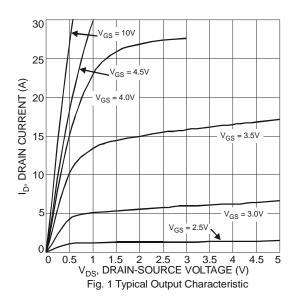


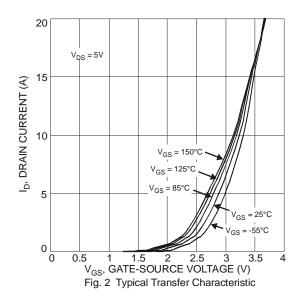
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| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
|--|----------------------|-----|------|------|------|--|--|
| OFF CHARACTERISTICS (Note 8) | | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 30 | - | - | V | $V_{GS} = 0V, I_D = 250 \ \mu A$ | |
| Zero Gate Voltage Drain Current | I _{DSS} | - | - | 1 | μA | $V_{DS} = 30V, V_{GS} = 0V$ | |
| Gate-Source Leakage | I _{GSS} | - | - | ±100 | nA | $V_{GS} = \pm 25V, V_{DS} = 0V$ | |
| ON CHARACTERISTICS (Note 8) | | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | 1.0 | 1.3 | 2.4 | V | $V_{DS} = V_{GS}, I_D = 250 \mu A$ | |
| Static Drain-Source On-Resistance | | - | 15 | 23 | mΩ | $V_{GS} = 10V, I_D = 10A$ | |
| | R _{DS} (ON) | - | 24 | 33 | mΩ | $V_{GS} = 4.5V, I_D = 7.5A$ | |
| Forward Transfer Admittance | Y _{fs} | - | 11 | - | S | $V_{DS} = 5V, I_D = 10.0A$ | |
| Diode Forward Voltage | V _{SD} | - | 0.69 | 1 | V | $V_{GS} = 0V$, $I_S = 1A$ | |
| DYNAMIC CHARACTERISTICS (Note 9) | | | | | | | |
| Input Capacitance | Ciss | - | 479 | - | pF | | |
| Output Capacitance | C _{oss} | - | 97 | - | pF | V _{DS} = 15V, V _{GS} = 0V, f = 1.0MHz | |
| Reverse Transfer Capacitance | C _{rss} | - | 61 | - | pF | 1 - 1.00012 | |
| Gate Resistance | Rg | 0.4 | 1.1 | 1.6 | Ω | $V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$ | |
| Total Gate Charge V _{GS} = 4.5V | Qg | - | 5.0 | - | nC | | |
| Total Gate Charge V _{GS} = 10V | Qg | - | 10.5 | - | nC | | |
| Gate-Source Charge | Q _{gs} | - | 1.8 | - | nC | V _{DS} = 15V, I _D = 10A | |
| Gate-Drain Charge | Q _{gd} | - | 1.6 | - | nC | 1 | |
| Turn-On Delay Time | t _{D(on)} | - | 2.9 | - | ns | | |
| Turn-On Rise Time | tr | - | 7.9 | - | ns | V _{GS} = 10V, V _{DS} = 15V, | |
| Turn-Off Delay Time | t _{D(off)} | - | 14.6 | - | ns | $R_G = 3\Omega, R_L = 1.5\Omega,$ | |
| Turn-Off Fall Time | t _f | - | 3.1 | - | ns | 7 | |

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 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing. Notes:









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T_A = 150°C T_A = 125°C

T_A = 85°C

 $T_A = 25^{\circ}C$

 $T_A = -55^{\circ}C$

25

 $V_{GS} = 10V$ I_D = 10A

75

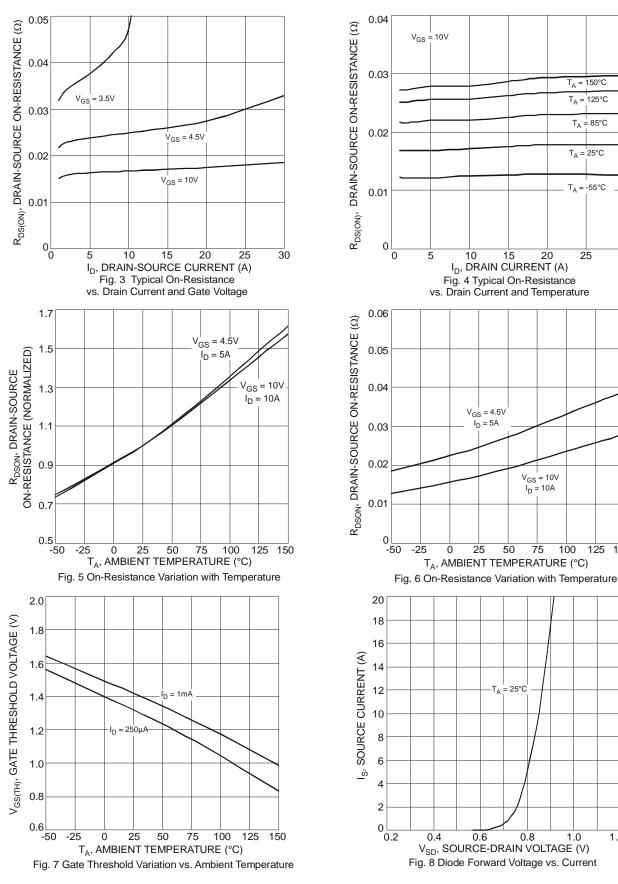
0.8

1.0

100

125 150

30



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1.2



1,000

C, CAPACITANCE (pF)

100

10

100

90

0.0001

0.001

P_(PK), PEAK TRANSIENT POIWER (W)

0

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f = 1MHz

30



Ciss

Coss

Fig. 9 Typical Total Capacitance

100

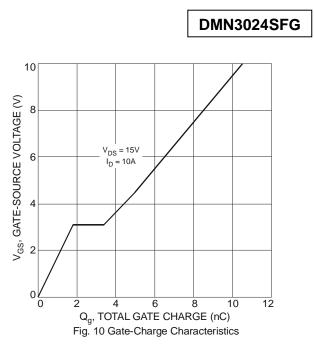
1,000

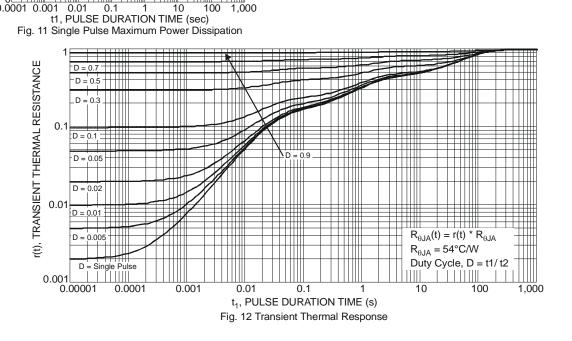
 $R_{\theta JA} = 61^{\circ}C/W$

 $R_{\theta JA(t)} = r_{(t)} * R_{\theta JA}$ $T_{J} - T_{A} = P * R_{\theta JA(t)}$

Single Pulse

C_{rss}





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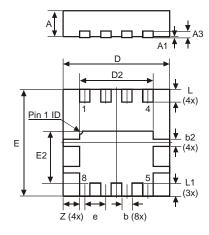
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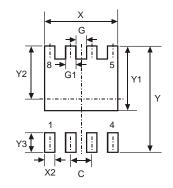
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Package Outline Dimensions



| POWERDI3333-8 | | | | | |
|----------------------|------|------|-------|--|--|
| Dim | Min | Max | Тур | | |
| D | 3.25 | 3.35 | 3.30 | | |
| Е | 3.25 | 3.35 | 3.30 | | |
| D2 | 2.22 | 2.32 | 2.27 | | |
| E2 | 1.56 | 1.66 | 1.61 | | |
| Α | 0.75 | 0.85 | 0.80 | | |
| A1 | 0 | 0.05 | 0.02 | | |
| A3 | - | - | 0.203 | | |
| b | 0.27 | 0.37 | 0.32 | | |
| b2 | - | _ | 0.20 | | |
| L | 0.35 | 0.45 | 0.40 | | |
| L1 | _ | _ | 0.39 | | |
| е | _ | _ | 0.65 | | |
| Ζ | _ | _ | 0.515 | | |
| All Dimensions in mm | | | | | |

Suggested Pad Layout



| Dimensions | Value (in mm) | | |
|------------|---------------|--|--|
| С | 0.650 | | |
| G | 0.230 | | |
| G1 | 0.420 | | |
| Y | 3.700 | | |
| Y1 | 2.250 | | |
| Y2 | 1.850 | | |
| Y3 | 0.700 | | |
| Х | 2.370 | | |
| X2 | 0.420 | | |





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